

**Table H.24 (H.27.1 of edition 3) – Electrical/electronic component fault modes table**  
(1 of 3)

Component type	Short <sup>a</sup>	Open <sup>b</sup>	Remarks
<b>Fixed resistors</b>			
Thin-film <sup>c</sup>		X	Includes SMD type
Thick-film <sup>c</sup>		X	Includes SMD type
Wire-wound <sup>c</sup> (single layer) enamelled or suitably coated		X	
All other types	X	X	
<b>Variable resistors</b> (for example, potentiometer/trimmer)			
Wire-wound (single layer)		X	
All other types	X <sup>d</sup>	X	
<b>Capacitors</b>			
X1 and Y types according to IEC 60384-14		X	
Metallized film according to IEC 60384-16 and IEC 60384-17		X	
All other types	X	X	
<b>Inductors</b>			
Wire-wound		X	
All other types	X	X	
<b>Diodes</b>			
All types	X	X	
<b>Semiconductor type devices like transistors</b>			
All types (for example, bipolar; LF; RF; microwave; FET; thyristor; Diac; Triac; Uni junction)	X <sup>d</sup>	X	<sup>e</sup>
<b>Hybrid circuit</b>	<sup>f</sup>	<sup>f</sup>	
<b>Integrated circuits</b>			
All types not covered by H.11.12	X <sup>g</sup>	X	For IC outputs, footnote <sup>e</sup> applies
<b>Optocouplers</b>			
According to IEC 60335-1	X <sup>h</sup>	X	
<b>Relays</b>			
Coils		X	
Contacts	X <sup>i</sup>	X	
<b>Reed-relays</b>	X	X	Contacts only
<b>Transformers</b>			
According to IEC 61558-2-6 or IEC 61558-2-16		X	
All other types	X <sup>d</sup>	X	
<b>Crystals</b>	X	X	<sup>j</sup>
<b>Switches</b>	X	X	<sup>k</sup>
<b>Connections</b> (jumper wire)		X	<sup>l</sup>
<b>Cable and wiring</b>		X	

Table H.24 (2 of 3)

Component type	Short <sup>a</sup>	Open <sup>b</sup>	Remarks
<b>Printed circuit board conductors</b> According to IEC 62326 series	X <sup>m</sup>	X <sup>n</sup>	
<b>Sensors</b> Polymeric type <b>thermistors</b> Ceramic type <b>thermistors</b>	X X	X X	<sup>o</sup>
<sup>a</sup> The conditions which have led to the design of the <b>clearances</b> and <b>creepage distances</b> according to Clause 20 on the assembly for which exclusion from the <b>fault</b> mode "short" is claimed shall be maintained over the lifetime of the <b>control</b> . These conditions shall be declared or documented as follows. <b>Control pollution</b> situation (Table 1, requirement 49). <b>Pollution</b> situation in the <b>micro-environment</b> of the <b>creepage distance</b> or <b>clearance</b> , if cleaner than that of the <b>control</b> , and how this is designed (documentation) (Table 1, requirement 79). <b>Rated impulse voltage</b> of the <b>control</b> (Table 1, requirement 75). <b>Rated impulse voltage</b> for the <b>creepage distance</b> or <b>clearance</b> , if different from that of the <b>control</b> , and how this is ensured (documentation) (Table 1, requirement 80). The values designed for tolerances of distances for which the exclusion from <b>fault</b> mode "short" is claimed. (declaration and documentation) (Table 1, requirement 81). <sup>b</sup> Only opening of one pin at any one time. <sup>c</sup> These components may be used for <b>protective impedance</b> , if the impedance of components complies with H.20.1.15.3 and withstands the impulse voltage test of 20.1.12 for at least <b>overvoltage category III</b> . <sup>d</sup> Short-circuit each pin in turn with every other pin; only two pins at a time. <sup>e</sup> For discrete or integrated thyristor type devices such as Triacs and SCRs, fault conditions shall include short circuit of any terminals with the third terminal open-circuited. The effect of any full wave type of component, such as a Triac going into a half-wave condition, either controlled or uncontrolled (thyristor or diode, respectively) shall be considered. <b>Failure</b> of a field effect based electronic power switching device (FET, MOSFET, IGBT) by loss of gate (base) control* resulting in a partial turn-on mode, causing an undefined state shall be considered. Testing and assessment criteria shall correspond to the specific <b>control</b> function and circuitry. Guidance might be given in parts 2. *Loss of gate control might occur due to, for example, an insufficient solder connection of the FET. <sup>f</sup> <b>Failure</b> modes for individual components of the <b>hybrid circuit</b> are applicable as described for the individual components in this table. <sup>g</sup> The short circuit of any two adjacent terminals and the short circuiting of - each terminal to the IC-supply, when applicable at the IC; - each terminal to the IC-ground, when applicable at the IC. The number of tests implied for <b>integrated circuits</b> may normally make it impracticable to apply all the relevant <b>fault</b> conditions or to assess the likely <b>hazards</b> from an appraisal of the circuit diagram of the <b>integrated circuit</b> . It is therefore permissible first to analyse in detail all the possible mechanical, thermal and electrical <b>faults</b> which may develop either in the <b>control</b> itself or its output, due to the malfunction of the <b>electronic devices</b> or other circuit components, separately or in any combination. Except for types evaluated by H.11.12, a <b>fault-tree</b> analysis shall be conducted to include the results of multiple steady-state conditions to outputs and programmed bi-directional terminals for the purpose of identifying additional <b>fault</b> conditions for consideration. The <b>failure</b> mode "short circuit" is excluded between isolated sections for such ICs that have isolated sections. The isolation between the sections shall comply with the requirements of 13.2 for <b>functional insulation</b> . <sup>h</sup> When optocouplers comply with 29.2.2 of IEC 60335-1:2010, the shorting between the input and output pins is not considered.			